



2.17.04

Form PTO-1595
Rev. 03/01
OMB No. 0651-0027 (exp. 5/31/2002)
Tab settings

02-23-2004

U.S. DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office
47434-00053



102675110

Attached original documents or copy thereof.

1. Name of conveying party(ies):
Hirofumi Konishi

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
Name: Hakko Corporation
Internal Address: _____

Street Address: _____
4-5, Shiokusa, 2-chome, Naniwa-ku
Osaka 556-0024, JAPAN

City: _____ State: _____ Zip: _____

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other

Execution Date: September 25, 2003

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: _____
A. Patent Application No.(s)
10/686,439
B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Sung I. Oh, Esq.

Squire, Sanders & Dempsey L.L.P.
801 South Figueroa Street
14th Floor
Los Angeles, California 90017-5554

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 3.41).....\$ 40.00
 Enclosed
 Authorized to be charged to deposit account
8. Deposit account number:
07-1853

(Attach duplicate copy of this page if paying by deposit account)

02/20/2004 DBYRME 00000107 10686439
01 FC:8021 40.00 OP

DO NOT USE THIS SPACE

9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Sung I. Oh Reg. No. 45,583 February, 2004
Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and documents:

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

Doc. ID 123963

ASSIGNMENT

WHEREAS, I, Hirofumi Konishi, residing at 438-17, Nagose, Kaizuka-shi, Osaka 597-0042, Japan, the undersigned inventor and the ASSIGNOR herein, have invented "CARTRIDGE TYPE SOLDERING IRON", for which I am filing an application for Letters Patent of the United States concurrently herewith, and of which inventions and improvements I am the sole owner; and

WHEREAS, Hakko Corporation, is a corporation organized and existing under the laws of Japan, having a place of business at 4-5, Shiokusa, 2-chome, Naniwa-ku, Osaka 556-0024, Japan, the ASSIGNEE herein, desires to acquire the entire right, title and interest in and to said inventions, applications and Letters Patent to be granted and issued thereon;

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) by the ASSIGNEE to me paid, and other valuable consideration, the receipt and legal sufficiency of all of which is hereby acknowledged, I, the said ASSIGNOR, have sold and do hereby sell, assign, transfer and set over unto said ASSIGNEE, its successors and assigns, the entire right, title and interest in and to said inventions and all improvements thereon, in and to said application for Letters Patent thereon, in and to applications pertaining to or based upon said inventions and applications, including divisional and continuing applications and continuations-in-part, and in and to any and all Letters Patent which may be granted and issued on said inventions and applications, or any of them, not only for, to and in the United States of America, its territories and possessions, but for, to and in all countries foreign thereto, together with and including all priority rights based upon any and all applications in the United States of America covered by this Assignment.

And for the above-named considerations, I do hereby agree that I will, at the request of said ASSIGNEE, execute any and all applications for Letters Patent for said inventions and any and all other papers and documents and do all other and further lawful acts that said ASSIGNEE may deem necessary or desirable to obtain Letters Patent on said inventions, to secure the grant of such Letters Patent and to perfect and vest in the ASSIGNEE the entire right, title and interest in the inventions, applications and Letters Patent.

And for the above-named considerations, I do hereby authorize and empower the ASSIGNEE, its successors and assigns, to apply for and obtain, in its or their own names, Letters Patent for the said inventions before competent International Authorities and in any and all countries foreign to the United States in which applications for Letters Patent can be so made or Letters Patent so obtained.

Dated: September 25, 2003

By Hirofumi Konishi
Hirofumi Konishi

LosAngeles/116184.1